

PMP5364_REVC BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
4	C1, C2, C3, C4	2.2uF	Capacitor, Ceramic, 100-V, X7R, 20%	1210	C3225X7R2A225M	TDK
1	C12	100uF	Capacitor, Aluminum, 25V, ZL Series	0.200 * 0.435 inch	25V ZL 100uF	Rubycon
3	C18, C19, C28	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	C1608X7R1C105M	TDK
1	C23	0.033uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H333K	TDK
1	C24	220pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H221K	TDK
1	C25	0.022uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H223K	TDK
1	C27	0.01uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H103K	TDK
1	C29	1000pF	Capacitor, Ceramic, 2kV, C0G, 10%	1812	Std	Std
1	C5	0.033uF	Capacitor, Ceramic, 250-V, X7R	1206	C3216X7R2E333M	TDK
3	C6, C7, C26	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
1	C8	470uF	Capacitor, Aluminum, 10V	0.315 inch	10V ZL 470uF 8x11.5mm	Rubycon
3	C9, C10, C100	47uF	Capacitor, Ceramic, 16-V, X5R, 20%	1210	Std	Std
7	D1, D3, D4, D9, D102, D103, D104	MMSD914	Diode, Switching, 100-V, 200-mA, 225-mW	SOD-123	MMSD914T1	On Semi
2	D100, D101	5.1V	Diode, Zener, 5.1-V	SOT23	BZX84C5V1LT1	ON Semiconductor
2	J1, J2	00-0-05-xx-00-00-0	Header, Single pin	0.072 x 1	8600-0-05-01-00-00-03-0	Mill-Max
2	J3, J4	52-0-05-xx-00-00-0	Header, Single pin	0.125 x 1	8952-0-05-01-00-00-03-0	Mill-Max
1	L1	2.2uH	Inductor, SMT, 24.3-A, 2.3-milliohm	0.785 x 0.855 inch	HC2LP-2R2-R	Coiltronics
1	L2	1mH	Inductor, SMT, 60mA	0.244 x 0.244 inch	PG0087.105NL	Pulse
2	Q1, Q7	CSD17301Q5A	MOSFET, NChan, 30V, 28A, 2milliohm	PWRPAK S0-8	CSD17301Q5A	
1	Q3	IRF6216	MOSFET, P-ch, 150-V, 2.2-A, 240-milliohms	SO8	IRF6216	International Rectifier
2	Q4, Q5	IRF7494	MOSFET, N-Chan, 150V, 44 milliohm, 5.2A	SO8	IRF7494	IR
3	Q6, Q100, Q101	MMBT3904	Bipolar, NPN, 40-V, 200-mA	SOT23	MMBT3904LT1	On Semi
1	Q9	MMBT3906	Bipolar, PNP, 40-V, 200-mA	SOT23	MMBT3906LT1	On Semi
1	R10	3.74k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R100, R101	1k	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R12	DNP	Do Not Populate	0603	N/A	N/A
1	R13	1.65k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R15	7.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R17	86.6k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R18	110k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	R2, R24, R26, R30	10k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R20, R21	1.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R23	249	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R3, R22, R28	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R5	0.047	Resistor, Chip, 1-W, 1%	2512	Std	Std
2	R7, R25	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R8, R11, R19	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	T1	PA0806.004NL	Transformer, Forward, Planar	0.850 x 0.920 inch	PA0806.004NL	Pulse
1	TP5	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100	5000	Keystone
1	U3	UCC2897APW	IC, Current-Mode Active Clamp PWM Controller	PW20	UCC2897APW	Texas Instruments
1	U7	TCMT1107	IC, Photocoupler, CTR = 80% - 160%	MF4	TCMT1107	Vishay
1	U8	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI

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